

CLAIM AMENDMENTS

1. (Currently Amended) A lead forming apparatus for a semiconductor device, comprising:

a holder which holds a semiconductor device ~~to be formed~~, the semiconductor device having a package and leads extending from a the package thereof;

two die assemblies set in parallel, ~~and each die assembly comprising a pair of top die and a bottom dies to be die~~ matched with each other, wherein the top and bottom dies in ~~said each of the~~ two die assemblies are positioned ~~to interpose so~~ the leads of the semiconductor device held on said holder ~~and are interposed between the top and bottom dies, which form the leads between them the top and bottom dies~~;

a mover which changes ~~a~~ relative distance between ~~said the top and bottom dies of the~~ two die assemblies.

2. (Currently Amended) The lead forming apparatus according to claim 1, wherein ~~said the top die comprises a punch to be in contact with~~ for contacting the leads and a roller, and said bottom die comprises a die ~~to be in contact with~~ for contacting the leads and a cam ~~to be in contact with~~ for contacting the roller.

3. (Currently Amended) The lead forming apparatus according to claim 2, wherein ~~said the cam comprises a first block to be in contact with said~~ for the roller, a second block having a slope ~~to be engaged with~~ for engaging the first block, and an adjuster which moves the second block relative to the first block, ~~whereby wherein~~ the first block can be moved on the slope of the second block.

4. (Currently Amended) The lead forming apparatus according to claim 2, wherein ~~said the top die comprises a first block to be in contact with~~ for contacting the leads, a second block having a slope ~~to be engaged with~~ for engaging the first block, and an adjuster which moves the second block relative to the first block, wherein the first block can be moved on the slope of the second block.

5. (Currently Amended) The lead forming apparatus according to claim 1, wherein ~~said the die comprises a first block to be in contact with~~ for contacting the leads at distal ends ~~thereof of the leads~~, a second block ~~to be in contact with~~ for contacting the leads at proximal ends ~~thereof of the leads~~, and an adjuster which makes the second block contact ~~with the~~ leads to change ~~a~~ bending angle of the leads.

6. (Currently Amended) The lead forming apparatus according to claim 1, wherein ~~said the~~ holder comprises a first block ~~to support a~~ for supporting the package of the semiconductor device, a second block having a slope ~~to engage with~~ for engaging the first block, and an adjuster ~~to move~~ for moving the second block relative to the first block, wherein the first block can be moved on the slope of the second block.

7. (Currently Amended) The lead forming apparatus according to claim 1, wherein ~~said the~~ holder comprises two parts fixed to ~~said the~~ bottom dies, each of the two parts supporting ~~a~~ the package of the semiconductor device.

8. (Currently Amended) The lead forming apparatus according to claim 1, wherein ~~said the~~ holder comprises a pair of two parts supporting ~~a~~ the package of the semiconductor device, and a shifter which shifts relative positions of the two parts.

9. (Currently Amended) The lead forming apparatus according to claim 1, further comprising a guide roller which holds one of ~~said the~~ top dies ~~in of~~ in of the two die ~~assembly assemblies~~ and ~~allows them to decrease or increase~~ changes relative distance between ~~them~~ the dies.

10. (Currently Amended) The lead forming apparatus according to claim 1, further comprising a sensor which detects relative distance between the two die assemblies, and a controller which drives ~~said the~~ mover such that the relative distance detected by ~~said the~~ sensor has a predetermined value.

11. (Currently Amended) A lead forming system comprising:
~~two first and second~~ units of a lead forming apparatus for a semiconductor device, and
a carrier which ~~takes~~ carries a semiconductor device formed by ~~one~~ the first of the units, rotates the semiconductor device by 90 degrees, and carries the rotated semiconductor device to the ~~other~~ second of the units; ~~wherein said lead forming apparatus comprising:~~
a holder which holds a semiconductor device ~~to be formed~~, the semiconductor device having a package and leads extending from ~~a~~ the package ~~thereof~~;
two die assemblies set in parallel ~~and~~ , each die assembly comprising ~~a pair of~~ top and bottom dies matched with each other;
a mover which changes ~~a~~ relative distance between ~~said the~~ top and bottom dies of the two die assemblies, wherein the top and bottom dies in ~~said the~~ two die

assemblies are positioned ~~to interpose~~ so the leads of the semiconductor device held on said holder ~~and~~ are interposed between the top and bottom dies, which form the leads between them.

12. (Currently Amended) A method for forming leads of a semiconductor device with a lead forming apparatus having two die assemblies set in parallel ~~and~~, each die assembly comprising ~~a pair of~~ top and bottom dies matched with each other, the method comprising ~~the steps of:~~

measuring ~~a~~ size of ~~the~~ semiconductor device before lead forming;
comparing the ~~measured~~ size measured with a normal ~~value~~ size;
adjusting ~~the~~ positions of components in the lead forming apparatus according to ~~a~~ difference between the ~~measured~~ size measured and ~~a~~ the normal ~~value~~ size; and
forming the leads of the semiconductor device ~~by using~~ the lead forming apparatus, wherein the top and bottom dies form leads interposed between them.

13. (Currently Amended) A method for forming leads of a semiconductor device with a lead forming apparatus having two die assemblies set in parallel ~~and~~, each die assembly comprising ~~a pair of~~ top and bottom dies matched with each other, the method comprising ~~the steps of:~~

forming the leads of the semiconductor device ~~by using~~ the lead forming apparatus, wherein the top and bottom dies form leads interposed between them;
measuring ~~a~~ size of the semiconductor device after forming the ~~lead forming~~ leads; and
adjusting positions of components in the lead forming apparatus according to ~~a~~ difference between the ~~measured~~ size measured and ~~a~~ normal ~~value~~ size.